

A) 1. (Amended) A soldering flux comprising 0.1 - 70 mass percent of an organic acid selected from rosins and carboxylic acid anhydrides, 5 - 40 mass percent of a solvent, and a total of 10 - 95 mass percent of a thermosetting resin and a curing agent, wherein during soldering of a component, the flux exhibits a function of securing the component by the thermosetting resin.

2. (Amended) A soldering flux as described in claim 1 wherein the organic acid contains a carboxylic acid anhydride.

3. (Amended) A soldering flux as described in claim 1 wherein the organic acid contains a rosin.

[Please add the following claims:

A- 15/ 17. A method as claimed in claim 13 wherein the first member comprises a chip component and the second member comprises a printed circuit board.

16/ 18. A method as claimed in claim 17 wherein the first member comprises a flip chip.

17/ 19. A method as claimed in claim 14 wherein the first member comprises a chip component and the second member comprises a printed circuit board.

20. A method as claimed in claim 19 wherein the first